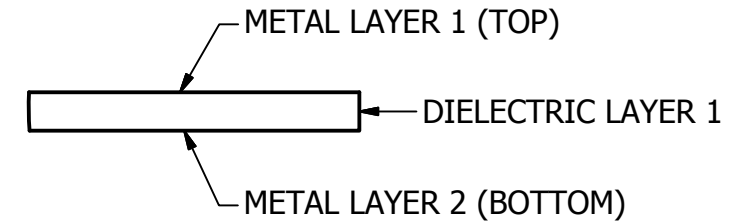
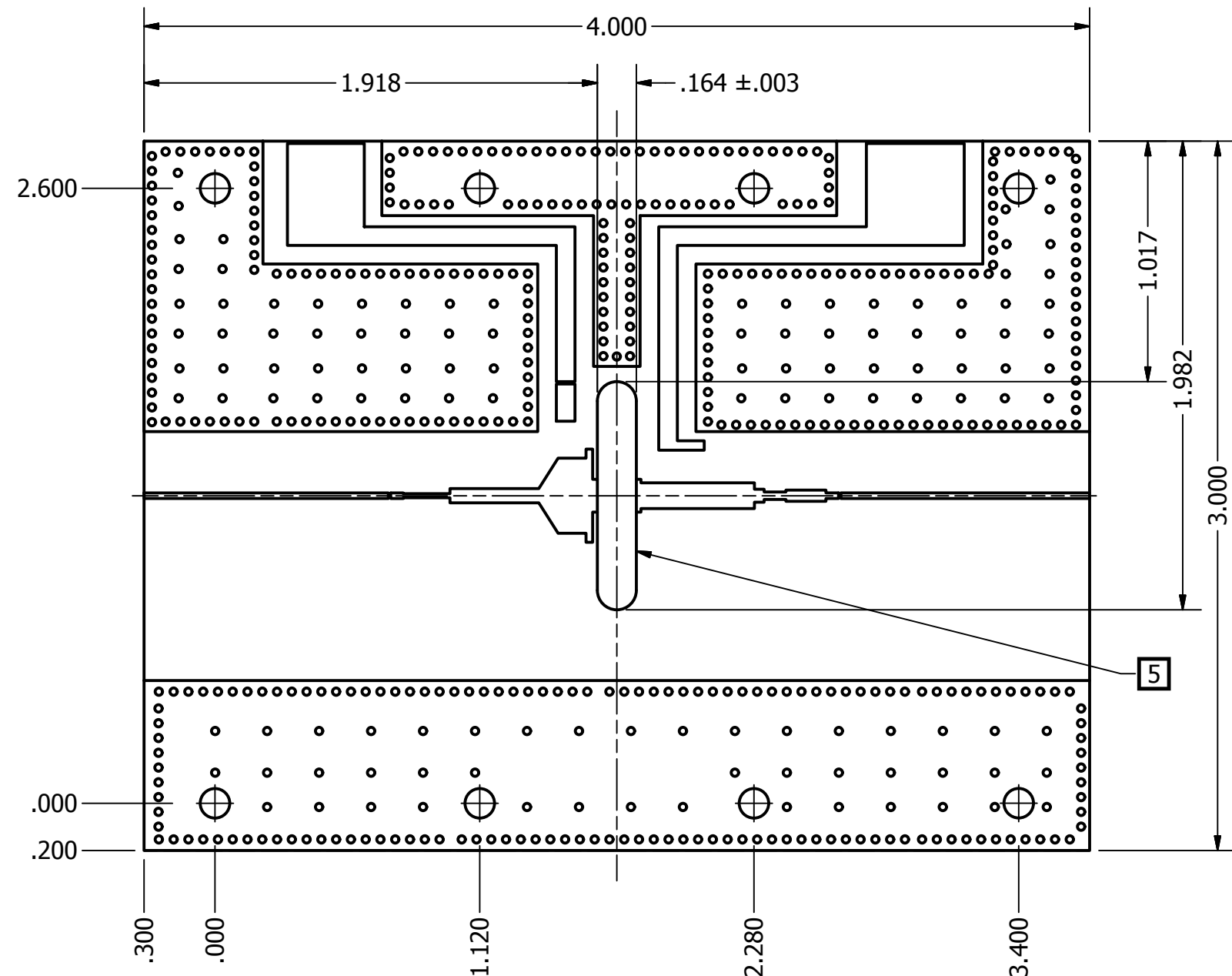



REVISION HISTORY				
ECN	REV	DESCRIPTION	DATE	APPROVED
	-	NEW RELEASE	4/14/11	I.MEDINA

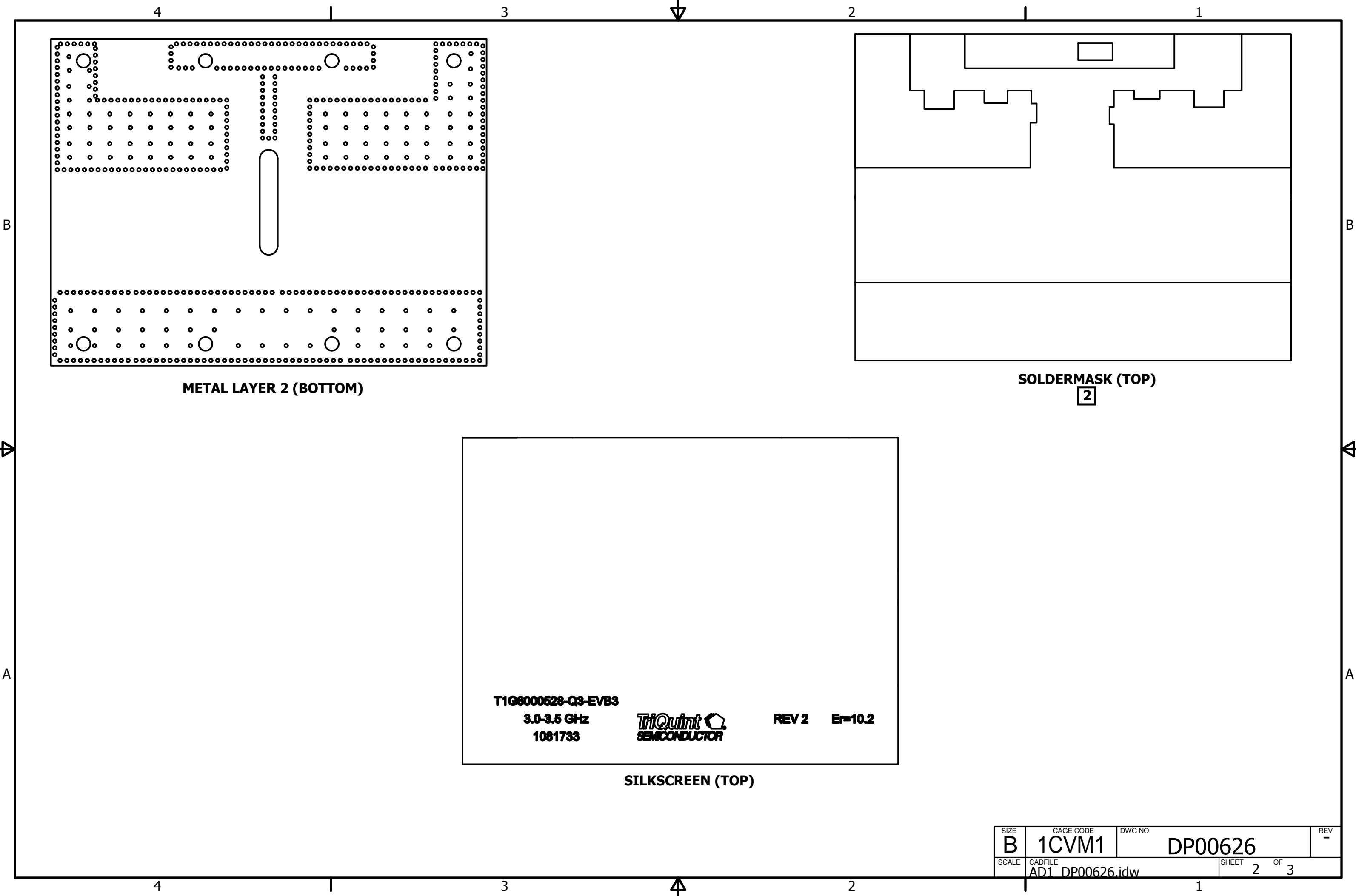


DETAIL A
SCALE 20 : 1

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:**
 - DIELECTRIC LAYER 1 - ROGERS 3210, 0.025 THICK
 - METAL LAYER 1 - 2 - 1.0 OZ. COPPER
 - SOLDERMASK - BLUE
 - SILKSCREEN - WHITE
- SOLDERMASK IN AREAS INDICATED. 0.001 INCHES THICK MAX**
- COPPER IS PULLED BACK 0.003 ON METAL LAYER 1 (TOP), METAL LAYER 2 (BOTTOM), FROM EDGE OF PCB.**
- PLATING:**
 - A. ELECTROPLATE COPPER 0.0012 INCH THICK
 - B. IMMERSION GOLD (2-6um) IAW IPC-4552 CLASS 38.
- SLOT SHALL NOT BE PLATE THRU**
- CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001 INCHES OF CAD DATA BASE.**
- ALL HOLES TO BE LOCATED WITHIN ± 0.0015 INCHES OF CAD DATABASE.**
- ALL BURRS SHALL BE REMOVED.**
- FABRICATE IN ACCORDANCE WITH IPC 6012A, CLASS 2 PER IPC 6011.**

		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: DECIMALS ANGLES .XX± .01 ± .1° .XXX± .005 .XXXX± .0010 DO NOT SCALE DRAWING	CONTRACT OR PRODUCT LINE		<div>TriQuintSEMICONDUCTOR</div>		500 W RENNER RD RICHARDSON TX 75080 TEL 972.994.8200 FAX 972.994.8504	
			APPROVALS	DATE	TITLE T1G6000528-Q3-EVB3 3.0-3.5 GHz BOARD			
			DRAWN IMedina CHECKED	4/14/2011				
			ENGR		SIZE B	CAGE CODE 1CVM1	DWG NO DP00626	REV -
NEXT ASSY	USED ON		MFG		SCALE	CADFILE AD1_DP00626.idw	SHEET 1	OF 3
APPLICATION		THIS DRAWING CONTAINS PROPRIETARY INFORMATION THAT MAY NOT BE USED WITHOUT THE WRITTEN CONSENT OF TRIQUINT SEMICONDUCTOR. FAILURE TO COMPLY MAY RESULT IN LEGAL ACTIONS OR CRIMINAL PROSECUTION	QA					



4

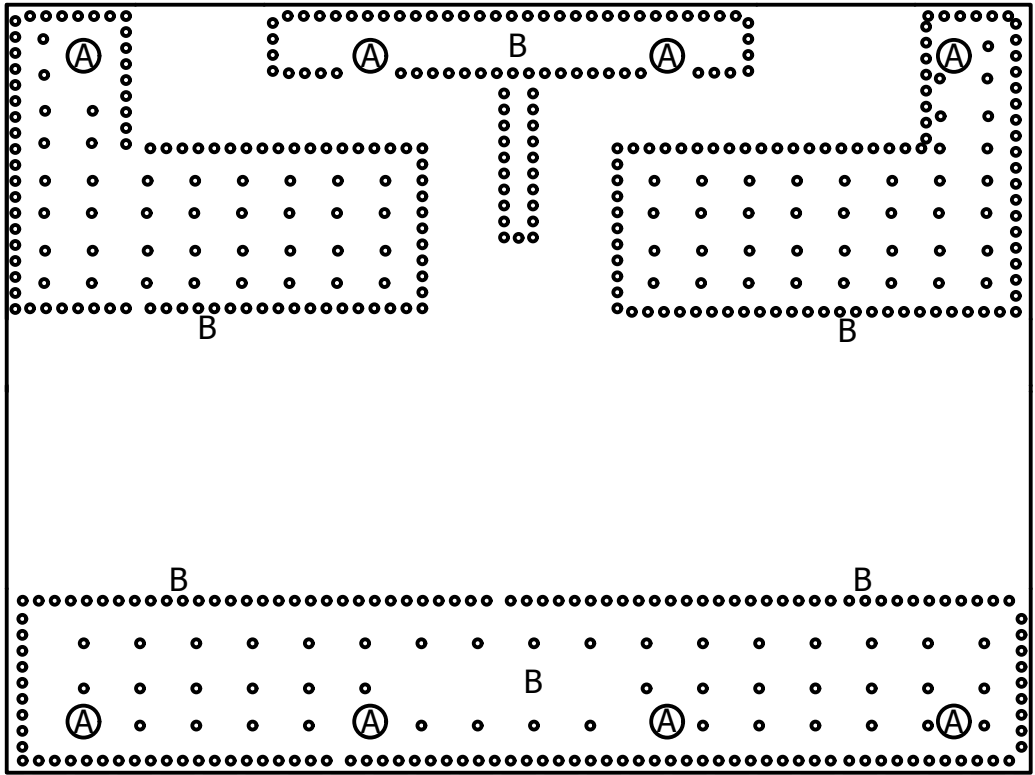
3

2

1

B

B



DRILL SIZE

DRILL TABLE			
SYMBOL	QUANTITY	HOLE SIZE	DESCRIPTION
A	8	0.125	PTH
B	517	0.031	PTH

A

A

SIZE	CAGE CODE	DWG NO	REV
B	1CVM1	DP00626	-
SCALE	CADFILE	SHEET	OF
	AD1_DP00626.idw	3	3

4

3

2

1